

ABSTRACT

[Problem to be Solved] To provide an information processing device that enables improvement of the processing quality of substrates by chemical mechanical polishing process.

[Solution] An information processing device 6 includes an information acquisition section 210b that acquires substrate polishing information including measured temperature distribution information indicating a measured value of a temperature distribution of a polishing surface when a polishing process for polishing a substrate with the polishing surface of a polishing pad is performed by a substrate polishing device 2 and device state information indicating a device state of the substrate polishing device 2, and an information generation section 210c that inputs the substrate polishing information acquired by the information acquisition section 210b into a learning model 10A to generate polishing surface temperature control information indicating a control amount of a polishing surface temperature adjustment section when a polishing process is performed by the substrate polishing device 2. The learning model 10A is a trained model that has learned a correlation between the substrate polishing information and the polishing surface temperature control information by machine learning.

FIG. 13